EXLA1V07

Automotive high current molded inductor





Product features

- · High current carrying capacity
- · AEC-Q200 qualified
- Low DCR, high efficiency
- · Magnetically shielded, low EMI
- Soft saturation
- Inductance range from 1 μH to 10 μH
- Current range from 5.0 A to 31.8 A
- EXLA1V0703: 8.7 mm x 8.3 mm footprint surface mount package in a 3.1 mm height
- EXLA1V0705: 8.7 mm x 8.3 mm footprint surface mount package in a 5.0 mm height
- EXLA1V0707: 8.7 mm x 8.3 mm footprint surface mount package in a 7.0 mm height
- · Alloy powder core material
- Moisture Sensitivity Level (MSL) 1

Applications

- · LED lighting
- Advanced driver assistance systems (ADAS)
- Adaptive cruise control (ACC)
- · Collision avoidance
- · Infotainment and cluster electronics
- · Battery management systems (BMS)
- · Electric pumps, motor control and auxiliaries
- Powertrain control module (PCU)/Engine control module (ECM)
- Electronic Control Units (ECU)

Environmental compliance and general specifications

- Operating temperature range: -55 °C to +155 °C (ambient plus self-temperature rise)
- Storage temperature range (component): -55 $^{\circ}$ C to +155 $^{\circ}$ C
- Solder reflow temperature:
 J-STD-020 (latest revision) compliant









Product specifications

Part number ⁴	OCL¹ (µH) ± 20%	I _{rms} ² (A)	I _{sat} ³ (A)	DCR (mΩ) typical @ +25 °C	DCR (mΩ) maximum @ +25 °C	D (mm) ±0.3
EXLA1V0703						
EXLA1V0703-1R0-R	1.0	21.8	28	4.55	5.0	6.6
EXLA1V0703-1R5-R	1.5	15.3	23.5	7.5	8.25	6.6
EXLA1V0703-2R2-R	2.2	13	17	12.4	13.7	6.2
EXLA1V0703-2R7-R	2.7	11.4	13.5	14	15.4	6.2
EXLA1V0703-3R3-R	3.3	10	13	16.3	18	6.2
EXLA1V0703-4R7-R	4.7	9.0	12.2	24.2	26.7	6.2
EXLA1V0703-5R6-R	5.6	7.3	11.5	30.1	33.2	6.2
EXLA1V0703-6R8-R	6.8	6.8	11	38.6	42.5	6.2
EXLA1V0703-8R2-R	8.2	5.9	9.0	44.3	48.73	6.2
EXLA1V0703-100-R	10	5.0	7.0	51	56.1	6.2
EXLA1V0705						
EXLA1V0705-2R2-R	2.2	14	17	5.8	6.4	
EXLA1V0705-3R3-R	3.3	13	14	10.4	11.44	
EXLA1V0705-4R7-R	4.7	11	13	14	15.4	
EXLA1V0705-5R6-R	5.6	10	11	15.6	17.2	
EXLA1V0707						
EXLA1V0707-1R0-R	1.0	25	31.8	2.55	2.81	6.7
EXLA1V0707-1R5-R	1.5	22	25.8	3.75	4.13	6.7
EXLA1V0707-1R8-R	1.8	21	23	4.05	4.46	6.7
EXLA1V0707-2R2-R	2.2	17.8	17.6	5.73	6.33	6.7
EXLA1V0707-3R3-R	3.3	15.1	15.1	8.56	9.42	6.7
EXLA1V0707-4R7-R	4.7	13.6	14	12.2	13.5	6.7
EXLA1V0707-5R6-R	5.6	11.4	12	13.67	15.03	6.5
EXLA1V0707-6R8-R	6.8	9.5	11	17.8	19.6	6.5
EXLA1V0707-100-R	10	7.0	9.0	24	26.4	6.5

^{1.} Open circuit inductance (OCL) test parameters: 100 kHz, 0.1 $V_{\rm msr}$, 0.0 Adc, +25 °C

Note: Rated operating voltage (across inductor) 40 V ref.

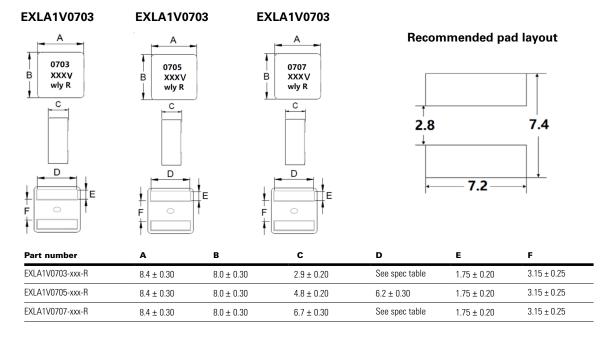
^{2.} l_{ms}: Heat rated current (l_{ms}) will cause the part temperature rise approximately ΔT of 40 °C. Circuit design, component, PCB trace size and thickness, airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application. The part temperature (ambient + temp rise) should not exceed +155 °C under worst case operating conditions.

^{3.} I_{sat} : Peak current for approximately 30% rolloff @ +25 °C

^{4.} Part number definition: EXLA1V0703-xxx-R
EXLA1V0703 = Product code and size
xxx= inductance value in µH, R= decimal point,
If no R is present then third digit equals the number of zeros
-R suffix = RoHS compliant

Automotive high current molded inductor

Mechanical parameters, schematic, pad layout (mm)



Part marking: 0703 or 0705 or 0707

xxx= Inductance value in µH (R= decimal point, if no R is present last digit equals number of zeros, V= vehicle, wly R= lot code

All soldering surfaces to be coplanar within 0.1 millimeters

Tolerances are \pm 0.3 millimeters unless stated otherwise

Dimensions of recommended PCB layout are reference only.

Pad layout tolerances are \pm 0.1 millimeters unless stated otherwise

Traces or vias underneath the inductor is not recommended.

Schematic



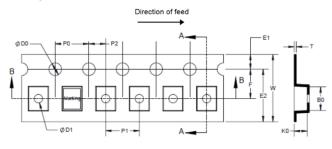
DCR Test

Packaging information (mm)

Supplied in tape and reel packaging

EXLA1V0703: 1500 parts per 13" diameter reel (EIA-481 compliant) EXLA1V0705: 800 parts per 13" diameter reel (EIA-481 compliant) EXLA1V0707: 750 parts per 13" diameter reel (EIA-481 compliant)

Drawing not to scale

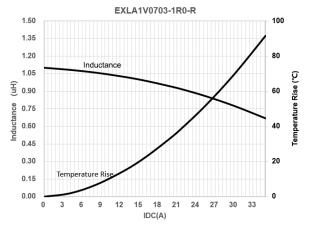


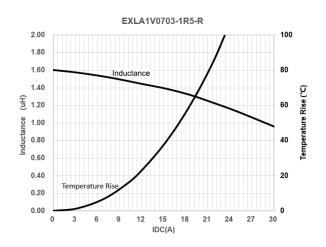
SECTION A-A

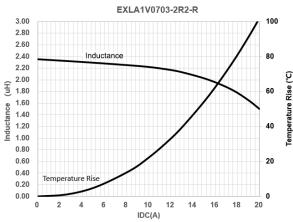


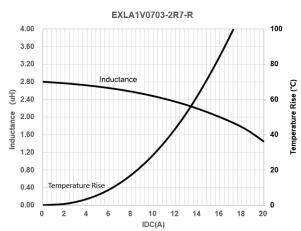
	EXLA1V0703	EXLA1V0705	EXLA1V0707
W ± 0.30	16.00	16.00	16.00
F ± 0.10	7.50	7.50	7.50
E1 ± 0.10	1.75	1.75	1.75
E2	14.25	14.25	14.25
P0 ± 0.10	4.00	4.00	4.00
P1 ± 0.10	12.00	12.00	12.00
P2 ± 0.10	2.00	2.00	2.00
D0 + 0.10/-0	1.50	1.50	1.50
D1 + 0.10/-0	1.50	1.50	1.50
A0 ± 0.10	8.80	8.80	8.80
B0 ± 0.10	8.40	8.40	8.40
K0 ± 0.10	3.30	5.30	7.30
T ± 0.05	0.35	0.40	0.50
P0 X 10 ± 0.20	40.0	40.0	40.0

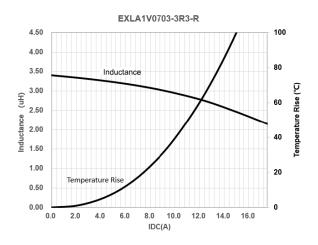
Inductance and temperature rise vs. current EXLA1V0703

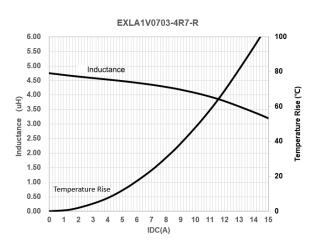




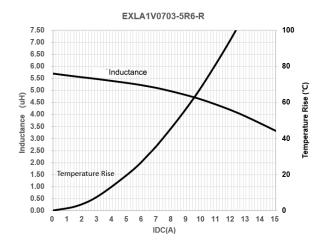


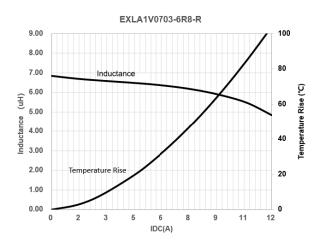


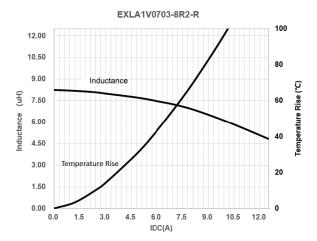


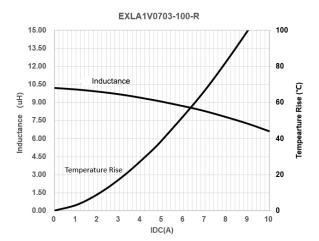


Inductance and temperature rise vs. current, continued EXLA1V0703

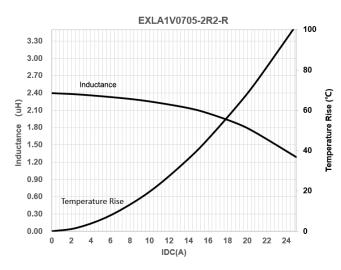


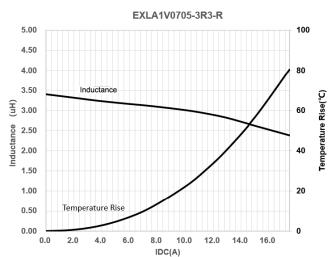


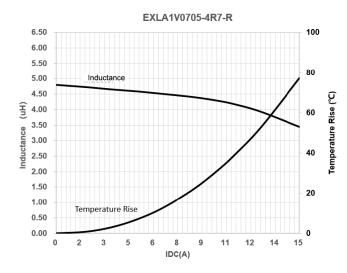


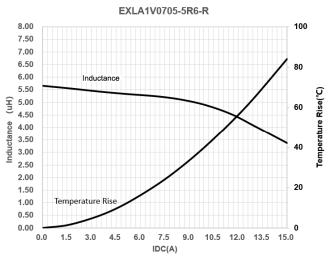


Inductance and temperature rise vs. current EXLA1V0705

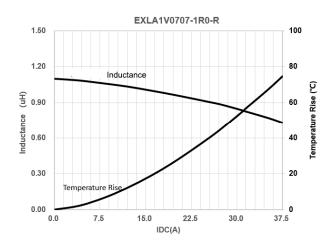


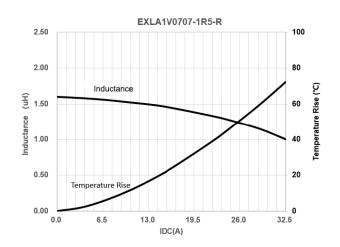


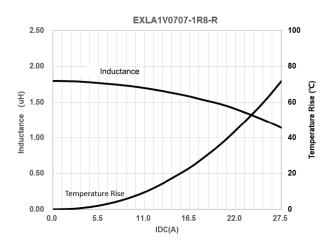


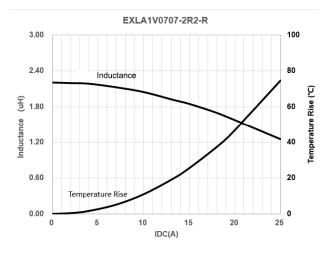


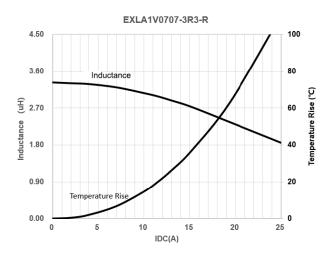
Inductance and temperature rise vs. current EXLA1V0707

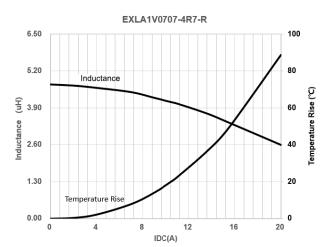




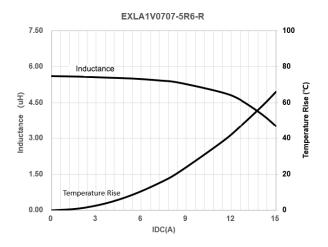


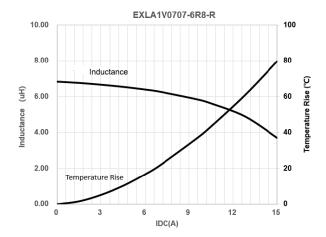


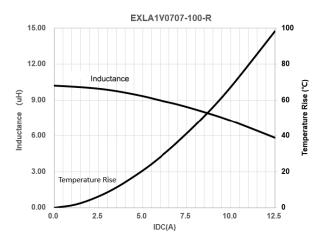


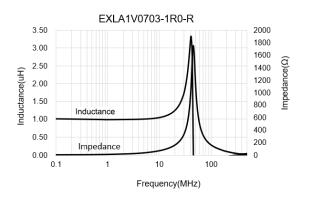


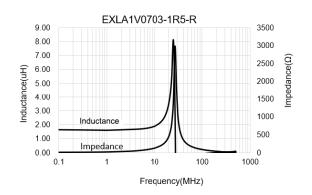
Inductance and temperature rise vs. current, continued EXLA1V0707

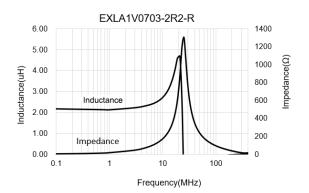


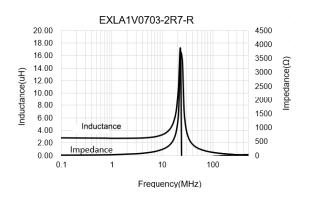


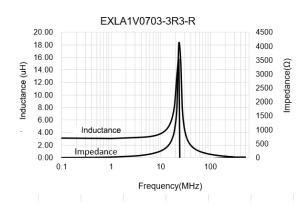


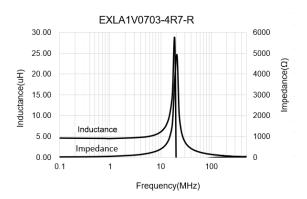


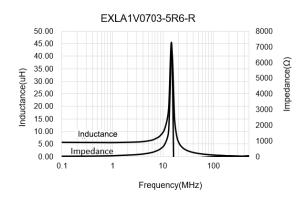


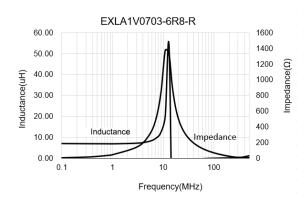


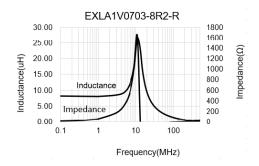


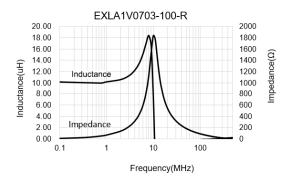


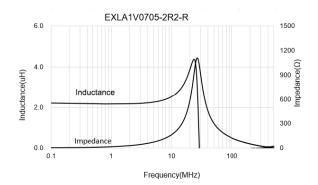


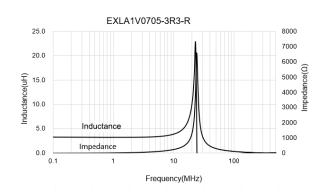


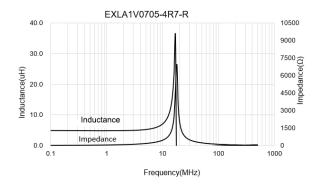


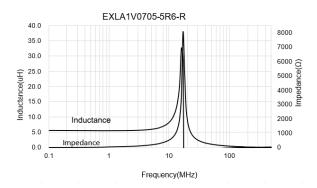


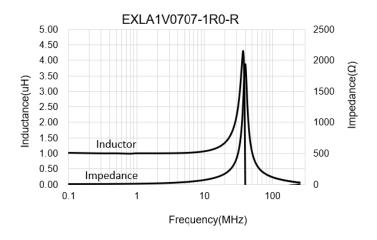


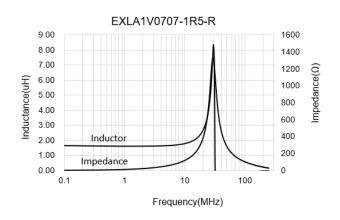


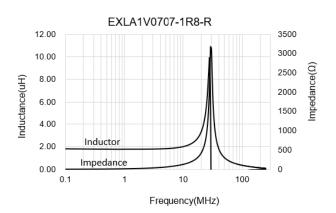


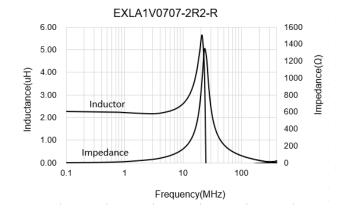


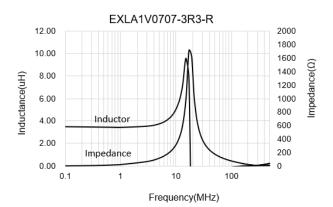


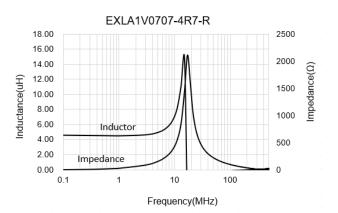


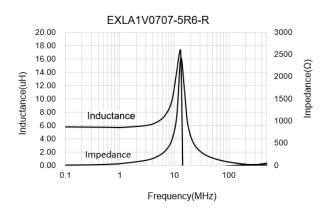


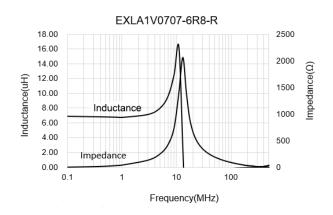


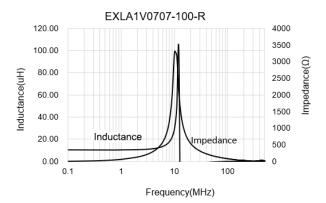












Solder reflow profile

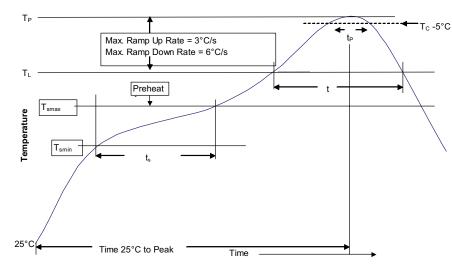


Table 1 - Standard SnPb solder (T_C)

Package thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2 - Lead (Pb) free solder (T_C)

Package thickness	Volume mm³ <350	Volume mm³ 350 - 2000	Volume mm³ >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 – 2.5 mm	260 °C	250 °C	245 °C
>2.5 mm	250 °C	245 °C	245 °C

Reference J-STD-020

Profile feature	Standard SnPb solder	Lead (Pb) free solder
Preheat and soak • Temperature min. (T _{smin})	100 °C	150 °C
• Temperature max. (T _{smax})	150 °C	200 °C
• Time (T _{smin} to T _{smax}) (t _s)	60-120 seconds	60-120 seconds
Ramp up rate T_L to T_p	3 °C/ second max.	3 °C/ second max.
Liquidous temperature (TL) Time (t_L) maintained above T_L	183 °C 60-150 seconds	217 °C 60-150 seconds
Peak package body temperature (Tp)*	Table 1	Table 2
Time (t _p)* within 5 °C of the specified classification temperature (T _C)	20 seconds*	30 seconds*
Ramp-down rate (T _p to T _L)	6 °C/ second max.	6 °C/ second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

 $^{^{\}star}$ Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

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